## APPLICATION DATA SHEET

## Electronic Version v14

Stylesheet Version v14.0

Title of Invention

STACKED CHIP-PACKAGING STRUCTURE

Application Type: regular, utility
Attorney Docket Number: 10792-US-PA

Correspondence address:

Customer Number: 31561

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Inventors Information:

Inventor 1:

Applicant Authority Type: Inventor
Citizenship: TW
Name prefix: Mr.
Given Name: Yu-Fang
Family Name: Tsai
Residence:

City of Residence: Kaohsiung

Country of Residence: TW

Address-1 of Mailing Address: No. 37-1, Lane 47, Houchang Rd., Nantz Chiu

Address-2 of Mailing Address:

City of Mailing Address: Kaohsiung

State of Mailing Address:

Postal Code of Mailing Address: 811
Country of Mailing Address: TW

Phone: Fax: E-mail:

Inventor 2:

Applicant Authority Type: Inventor

Citizenship: TW
Name prefix: Mr.

Given Name: Jung-Kun Family Name: Kang

Residence:

City of Residence: Kaohsiung

Country of Residence: TW

Address-1 of Mailing Address: No. 42, Lane 112, Tuku V Rd., Nantz Chiu

Address-2 of Mailing Address:

City of Mailing Address: Kaohsiung

State of Mailing Address:

Postal Code of Mailing Address:

Country of Mailing Address:

TW

Phone: Fax:

Fax:

Inventor 3:

Applicant Authority Type: Inventor
Citizenship: TW
Name prefix: Mr.

Given Name: Tsung-Yueh

Family Name: Residence:

City of Residence: Kaohsiung

Country of Residence: TW

Address-1 of Mailing Address: No. 27, Chianhe Rd., Gangshan Jen

Tsai

Address-2 of Mailing Address:

City of Mailing Address: Kaohsiung

State of Mailing Address:

Postal Code of Mailing Address: 820 Country of Mailing Address: TW

Phone: Fax:

E-mail:

Attorney Information:

practitioner(s) at Customer Number:

31561



as our attorney(s) or agent(s) to prosecute the application identified above, and to transact all business in the United States Patent and Trademark Office connected therewith.